

TM05P03AI

P-Channel Enhancement Mosfet

General Description

- Low $R_{DS(ON)}$
- RoHS and Halogen-Free Compliant

Applications

- Load switch
- PWM

General Features

$V_{DS} = -30V$ $I_D = -4.6A$

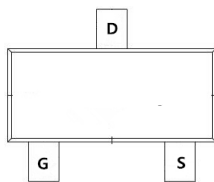
$R_{DS(ON)} = 36m\Omega$ (Typ.) @ $V_{GS} = -10V$

100% UIS Tested

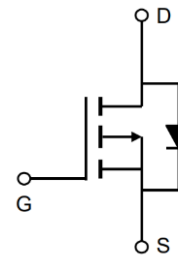
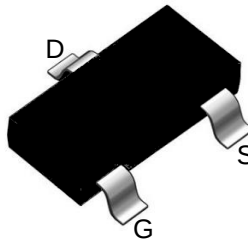
100% R_g Tested



I:SOT-23



Marking: A19T



Absolute Maximum Ratings ($T_C = 25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-30	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D @ T_A = 25^\circ C$	Continuous Drain Current	-4.6	A
$I_D @ T_A = 70^\circ C$	Continuous Drain Current	-3.0	A
IDM	Pulsed Drain Current ²	-17	A
$P_D @ T_A = 25^\circ C$	Total Power Dissipation ³	1.4	W
$P_D @ T_A = 70^\circ C$	Total Power Dissipation ³	0.9	W
TSTG	Storage Temperature Range	- 55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	- 55 to 150	$^\circ C$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	125	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹ ($t \leq 10s$)	85	$^\circ C/W$

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Electrical Characteristics ($T_J=25^{\circ}\text{C}$, unless otherwise noted)

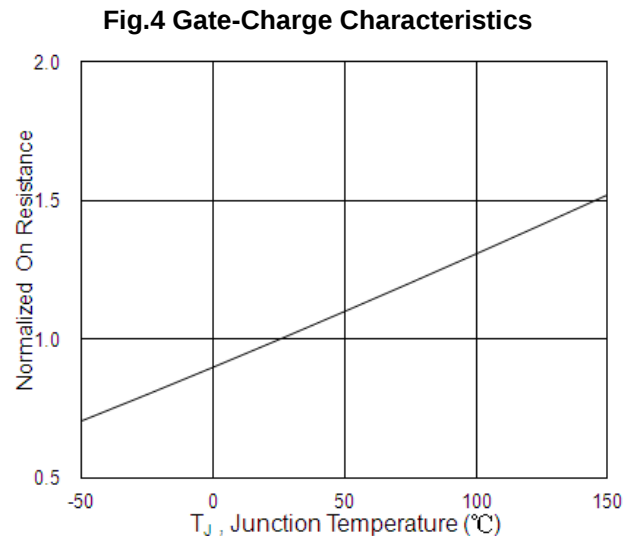
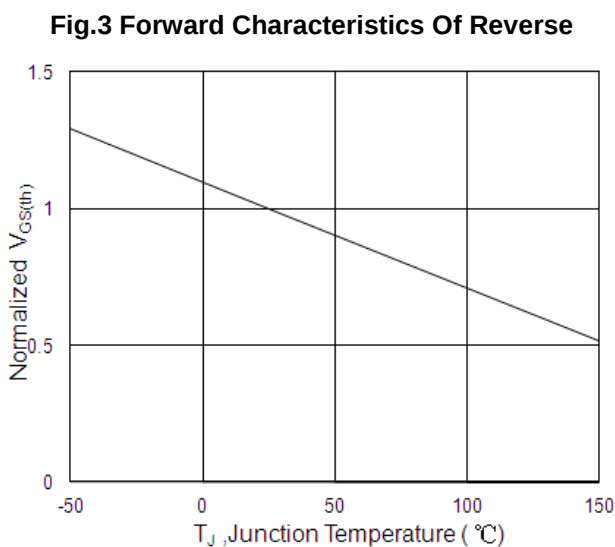
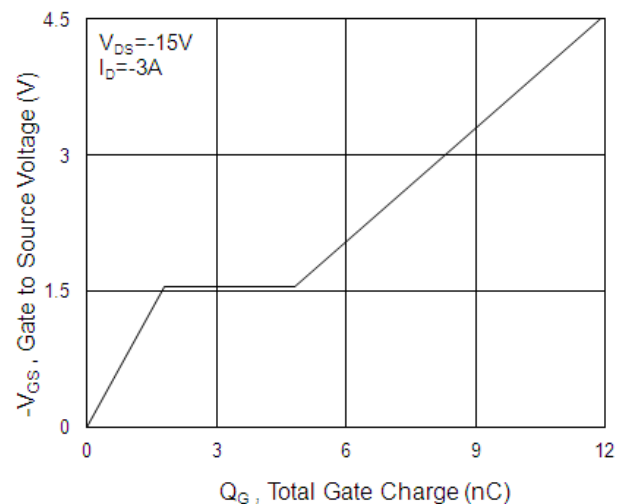
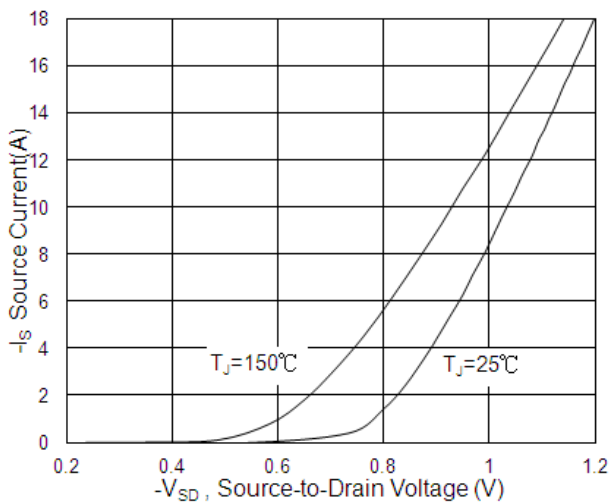
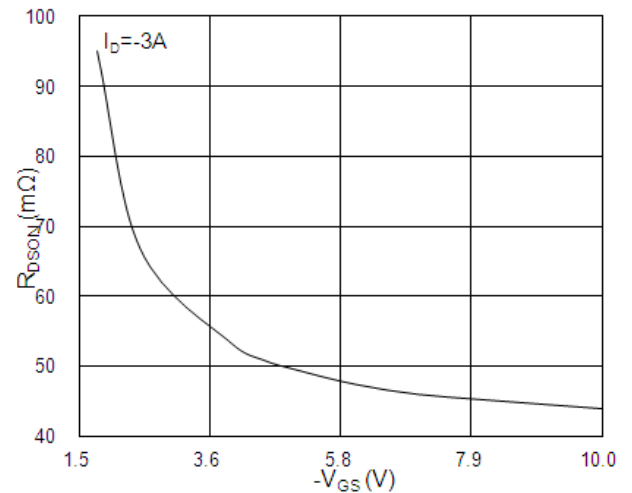
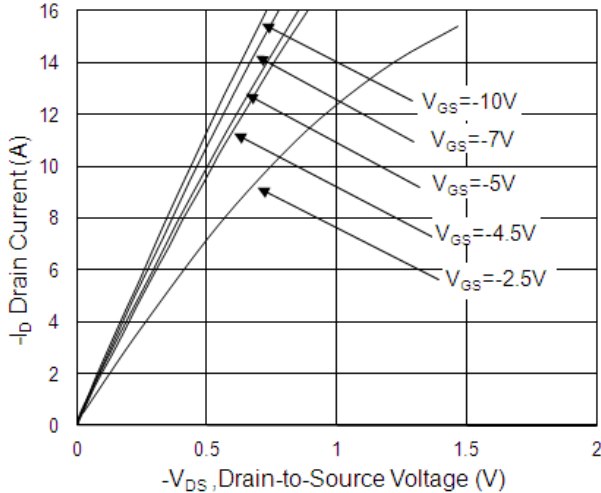
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	$V_{GS}=0V$, $I_D=-250\mu A$	-30	-32	---	V
$\Delta BVDSS/\Delta T_J$	BV _{DSS} Temperature Coefficient	Reference to 25°C , $I_D=-1\text{mA}$	---	-0.014	---	V/ $^{\circ}\text{C}$
RDS(ON)	Static Drain-Source On-Resistance	$V_{GS}=-10V$, $I_D=-3A$	---	36	50	m Ω
		$V_{GS}=-4.5V$, $I_D=-3A$	---	49	65	
VGS(th)	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=-250\mu A$	-0.5	-0.9	-1.1	V
$\Delta V_{GS(th)}$	V _{GS(th)} Temperature Coefficient		---	2.6	---	mV/ $^{\circ}\text{C}$
IDSS	Drain-Source Leakage Current	$V_{DS}=-24V$, $V_{GS}=0V$, $T_J=25^{\circ}\text{C}$	---	---	-1	μA
		$V_{DS}=-24V$, $V_{GS}=0V$, $T_J=55^{\circ}\text{C}$	---	---	-5	
IGSS	Gate-Source Leakage Current	$V_{GS}=\pm 12V$, $V_{DS}=0V$	---	---	± 100	nA
gfs	Forward Transconductance	$V_{DS}=-5V$, $I_D=-3A$	---	5.6	---	S
Q _g	Total Gate Charge (-4.5V)	$V_{DS}=-15V$, $V_{GS}=-4.5V$, $I_D=-3A$	---	11.9	---	nC
Q _{gs}	Gate-Source Charge		---	1.8	---	
Q _{gd}	Gate-Drain Charge		---	3	---	
Td(on)	Turn-On Delay Time	$V_{DD}=-15V$, $V_{GS}=-4.5V$, $R_G=3.3\Omega$, $I_D=-3A$	---	6.6	---	ns
T _r	Rise Time		---	27.8	---	
Td(off)	Turn-Off Delay Time		---	46.2	---	
T _f	Fall Time		---	20.6	---	
Ciss	Input Capacitance	$V_{DS}=-15V$, $V_{GS}=0V$, $f=1\text{MHz}$	---	390	---	pF
Coss	Output Capacitance		---	73	---	
Crss	Reverse Transfer Capacitance		---	71	---	
IS	Continuous Source Current ^{1,4}	$V_G=V_D=0V$, Force Current	---	---	-4.6	A
VSD	Diode Forward Voltage ²	$V_{GS}=0V$, $I_S=-1A$, $T_J=25^{\circ}\text{C}$	---	---	-1.2	V

Note :

- 1.The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
- 3.The power dissipation is limited by 150°C junction temperature
- 4.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.



Typical Characteristics



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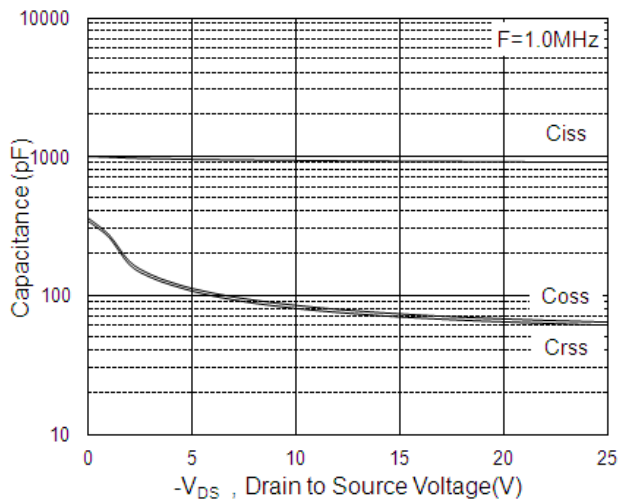


Fig.7 Capacitance

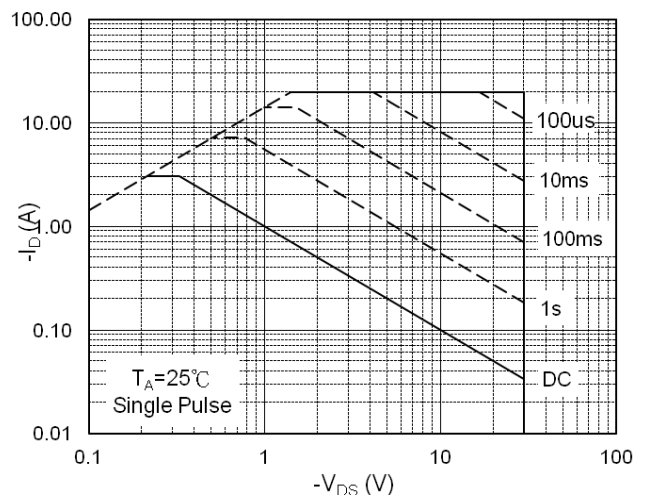


Fig.8 Safe Operating Area

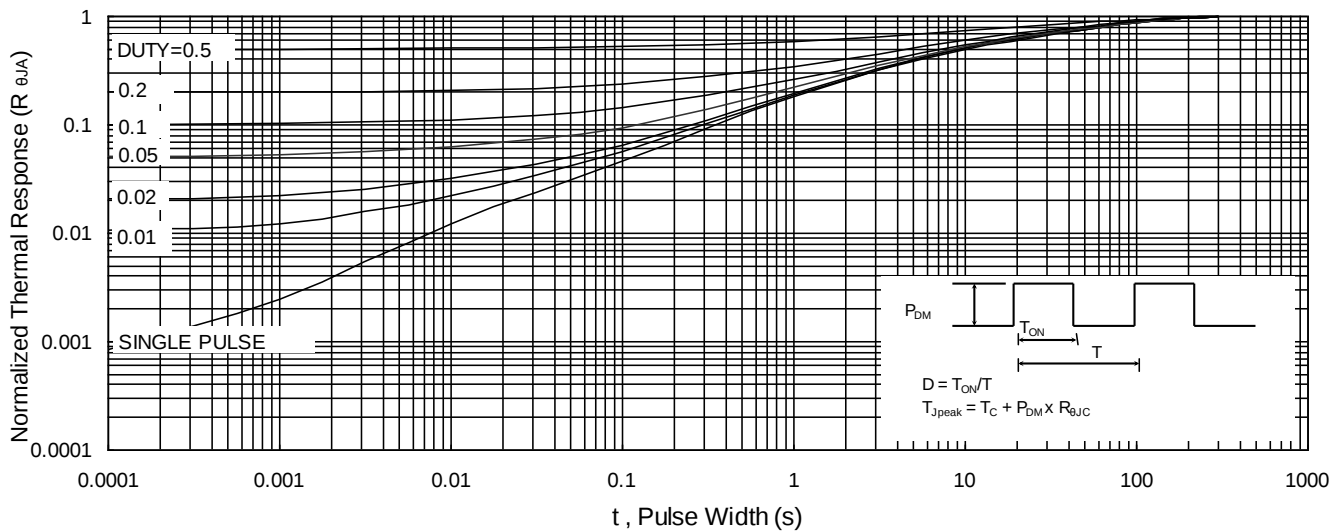


Fig.9 Normalized Maximum Transient Thermal Impedance

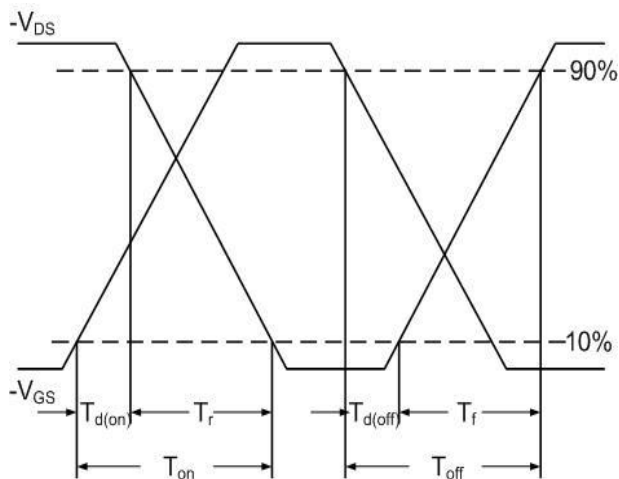


Fig.10 Switching Time Waveform

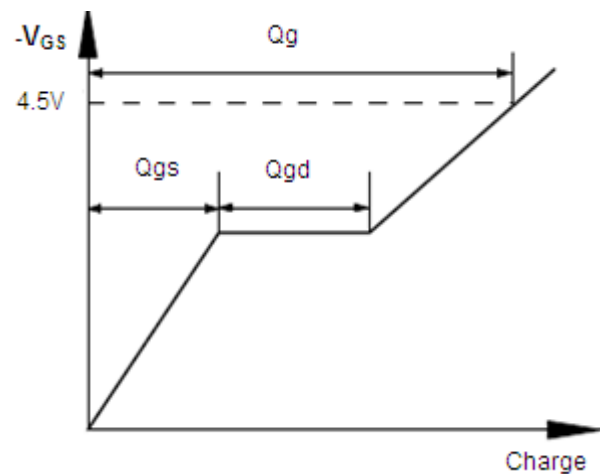
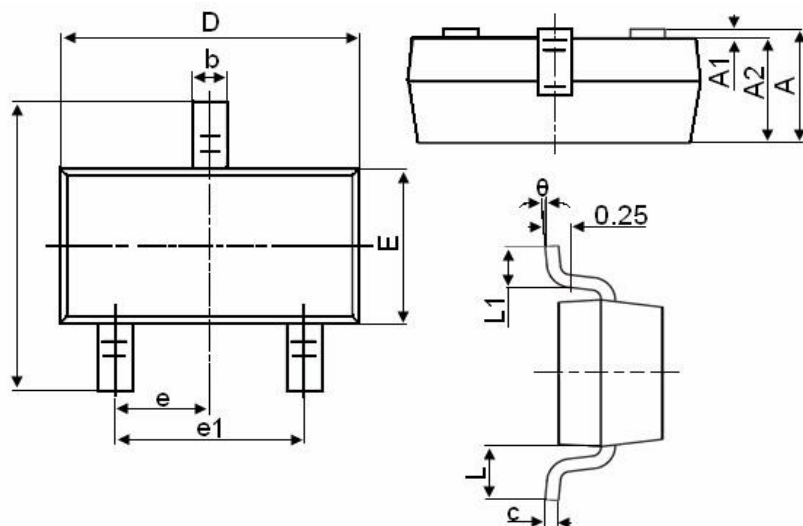


Fig.11 Gate Charge Waveform

Package Mechanical Data:SOT-23



Symbol	Dimensions in Millimeters	
	MIN.	MAX.
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
e	0.950TYP	
e1	1.800	2.000
L	0.550REF	
L1	0.300	0.500
θ	0°	8°